
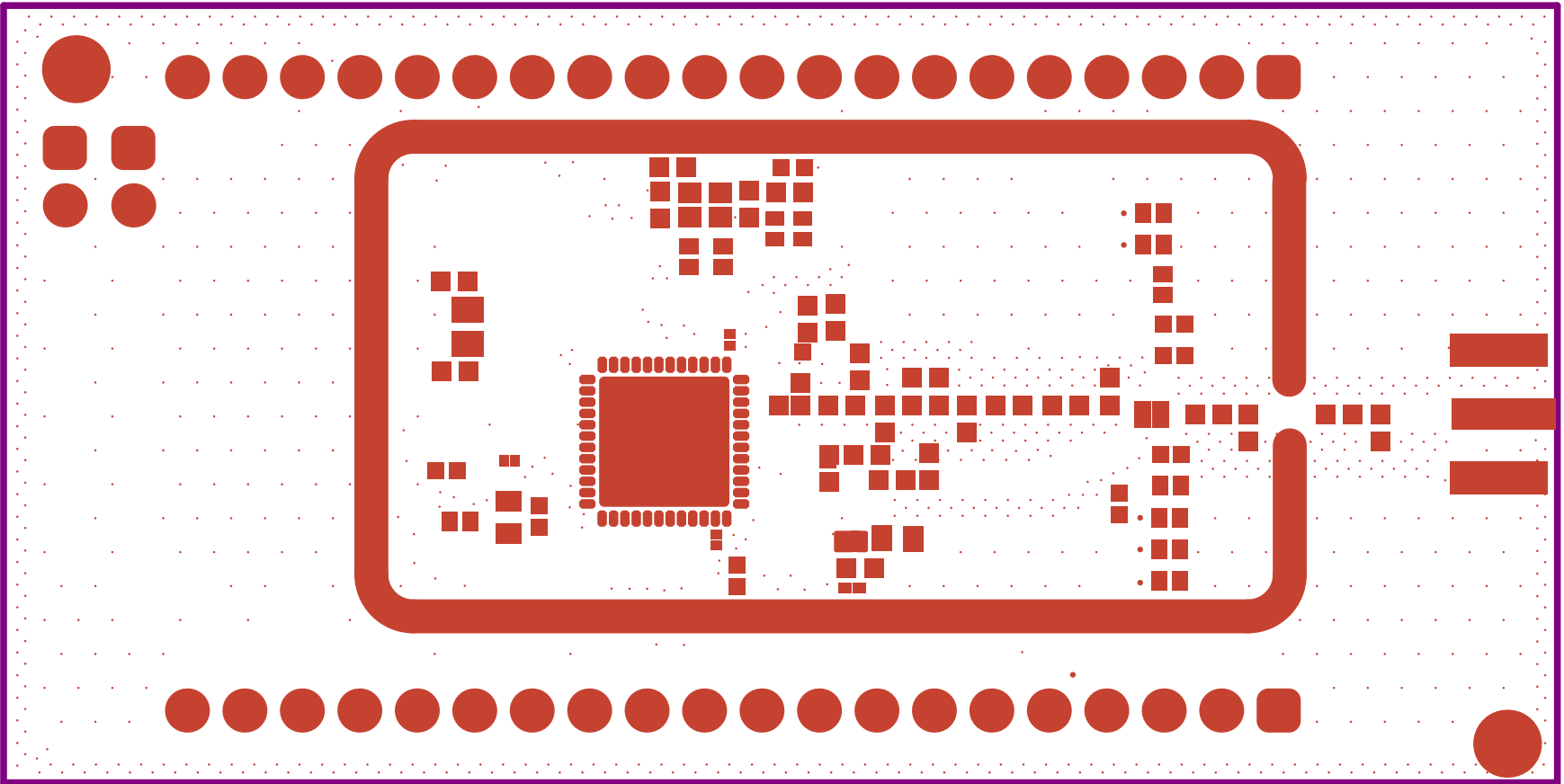

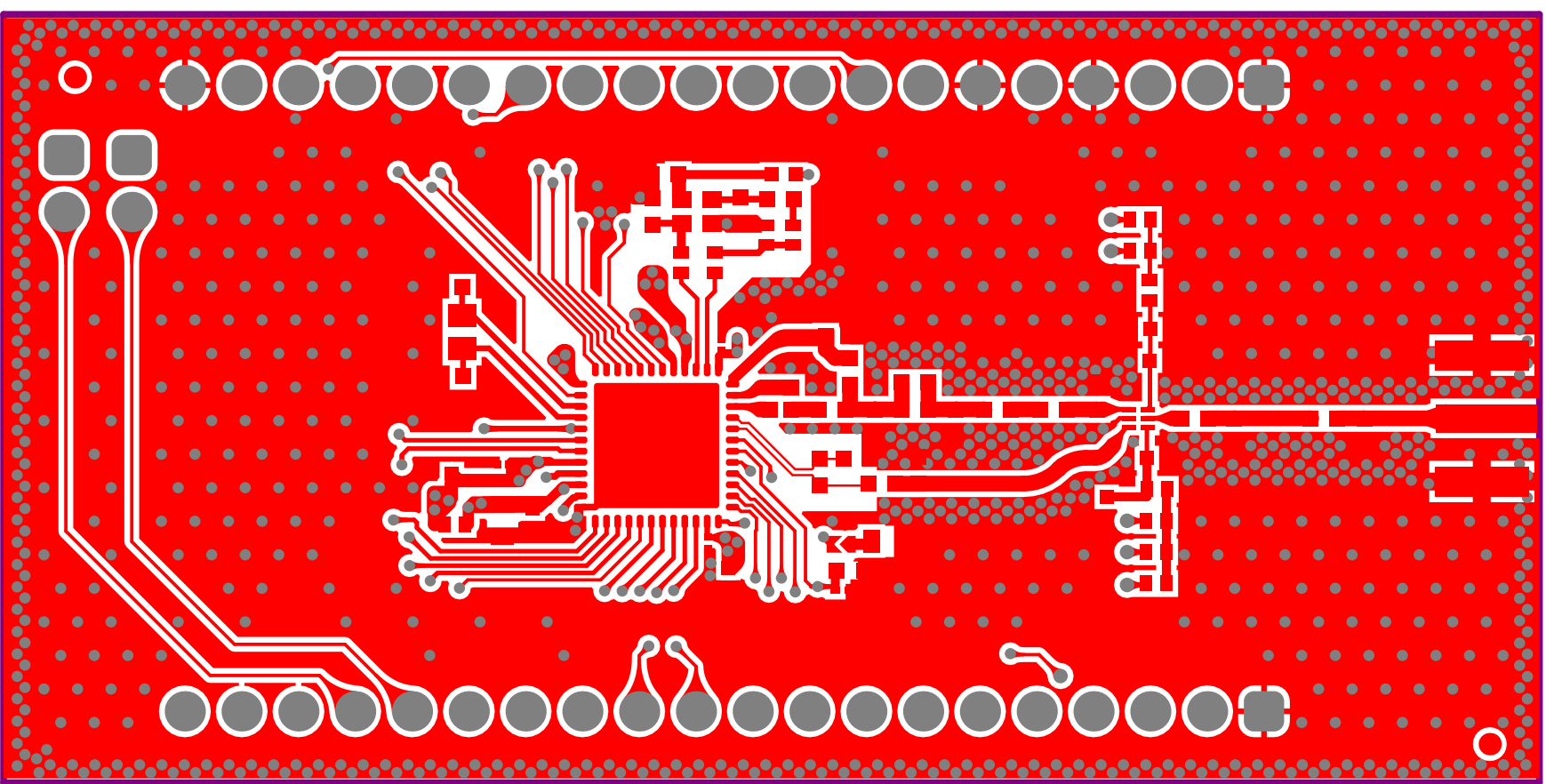



Project: STM32WL-QFN48-2Layers_Reference_Board		
Layer: Top Overlay	Gerber: .GTO	
Variant: [No Variations]	Ref: MB1791	
Date: 4-4-2022	Rev: A	




Project: STM32WL-QFN48-2Layers_Reference_Board		
Layer: Top Solder	Gerber: .GTS	
Variant: [No Variations]	Ref: MB1791	
Date: 4-4-2022	Rev: A	

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.39mil	3.5	
1	Top Layer		1.38mil		
	Dielectric 1	FR-4	27.95mil	5	
2	Bottom Layer		1.38mil		
	Bottom Solder	Solder Resist	0.39mil	3.5	
	Bottom Overlay				




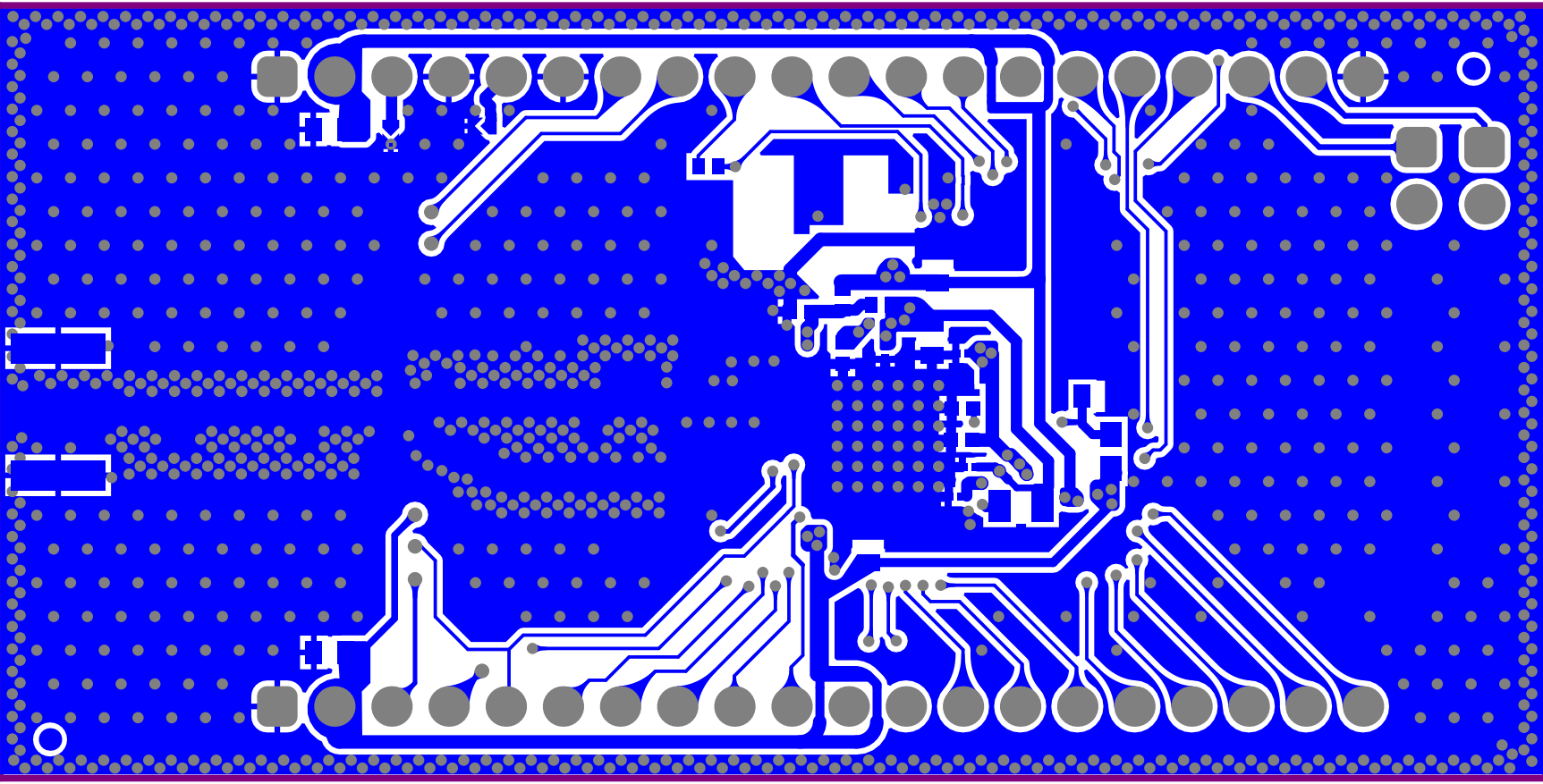
Project: STM32WL-QFN48-2Layers_Reference_Board		
Layer: Top Layer	Gerber: .GTL	
Variant: [No Variations]	Ref: MB1791	
Date: 4-4-2022	Rev: A	




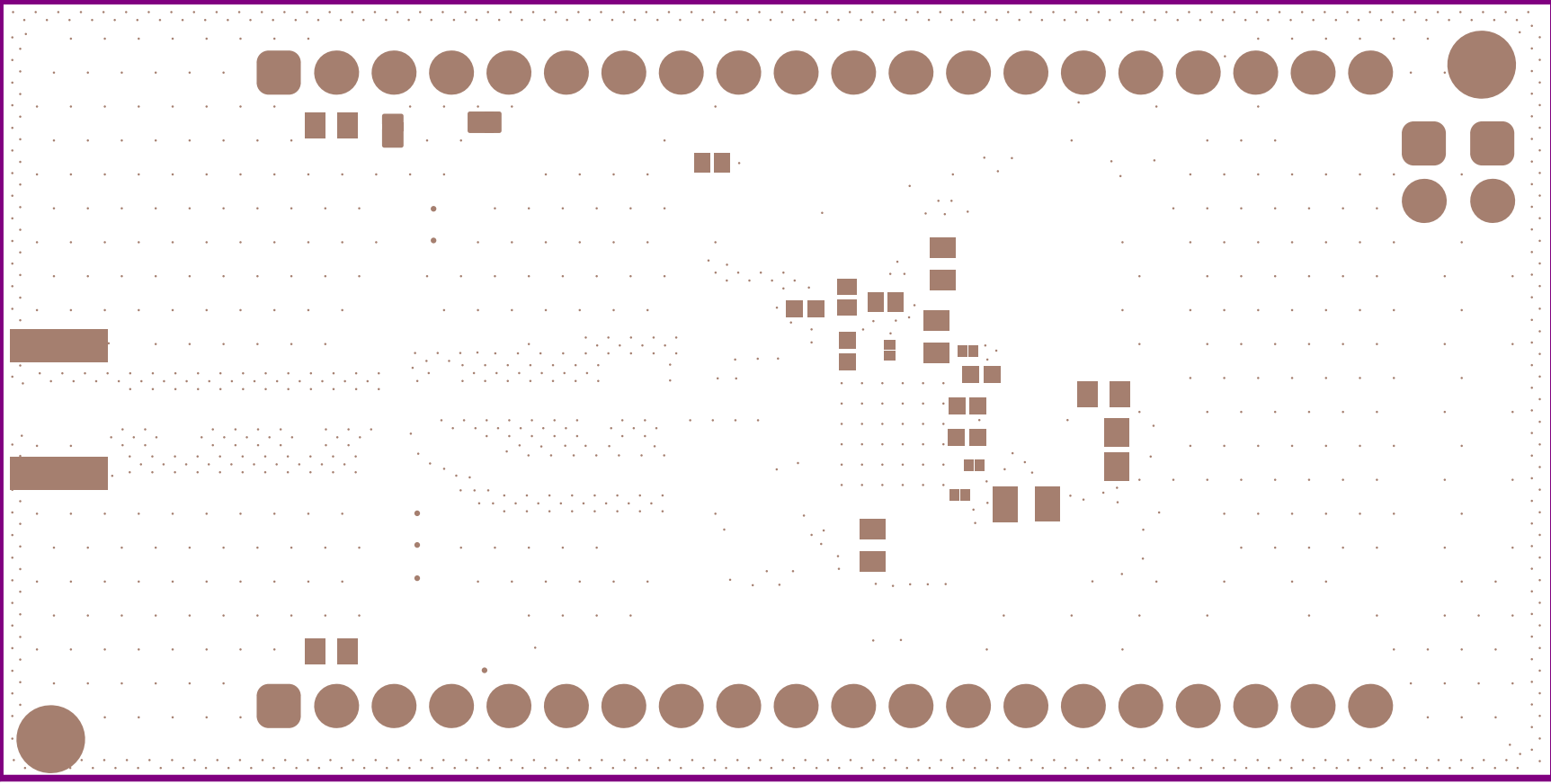
Project: STM32WL-QFN48-2Layers_Reference_Board		
Layer:	Gerber:	
Variant: [No Variations]	Ref: MB1791	
Date: 4-4-2022	Rev: A	




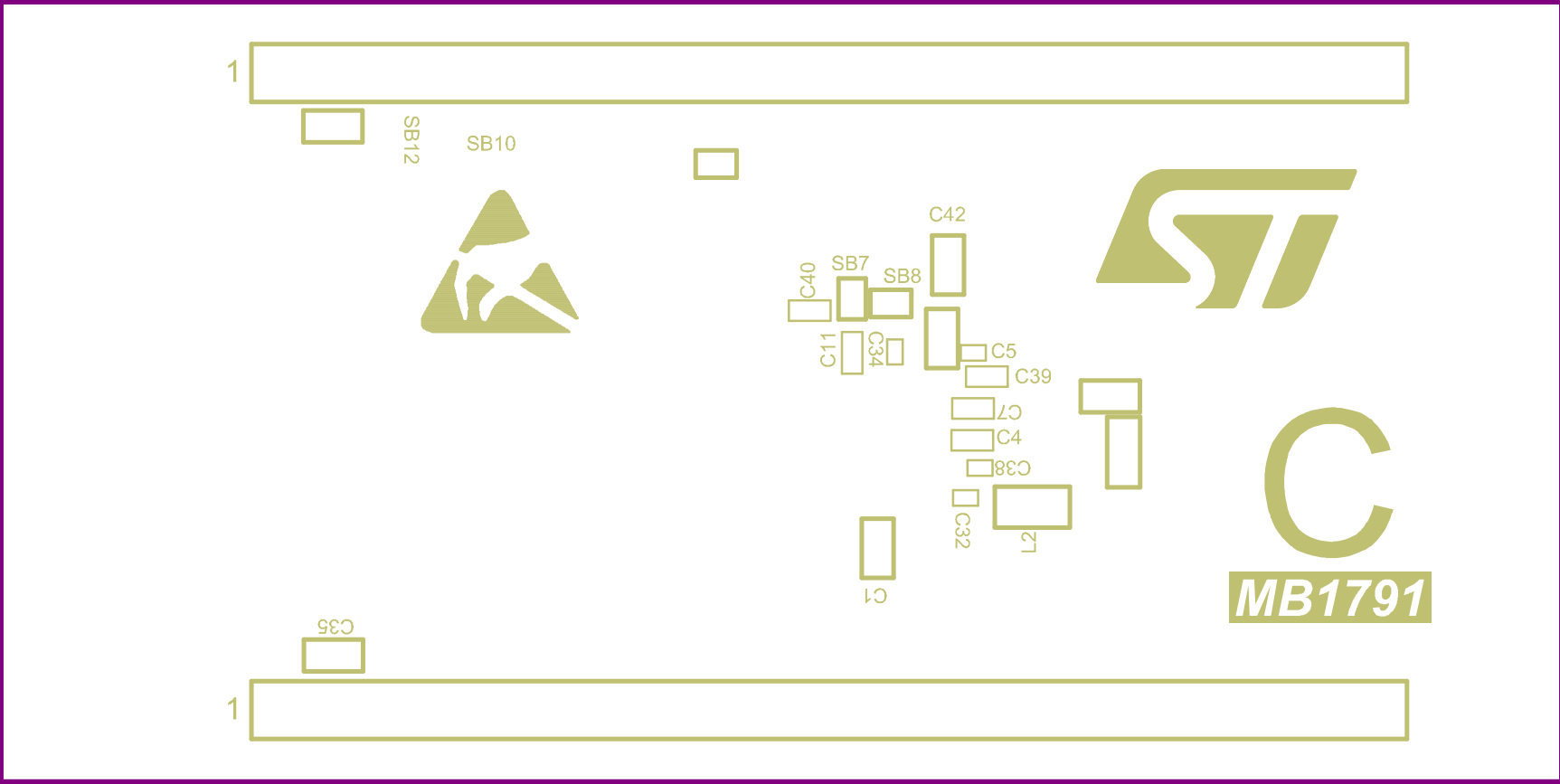
Project: STM32WL-QFN48-2Layers_Reference_Board		
Layer:	Gerber:	
Variant: [No Variations]	Ref: MB1791	
Date: 4-4-2022	Rev: A	




Project: STM32WL-QFN48-2Layers_Reference_Board		
Layer: Bottom Layer	Gerber: .GBL	
Variant: [No Variations]	Ref: MB1791	
Date: 4-4-2022	Rev: A	



Project: STM32WL-QFN48-2Layers_Reference_Board		
Layer: Bottom Solder	Gerber:.GBS	
Variant: [No Variations]	Ref: MB1791	
Date: 4-4-2022	Rev: A	



Project: STM32WL-QFN48-2Layers_Reference_Board		
Layer: Bottom Overlay	Gerber:.GBO	
Variant: [No Variations]	Ref: MB1791	
Date: 4-4-2022	Rev: A	

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)	Hole Length	Routed Path Length
□	44	1.000mm (39.37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)				-	-
▽	1128	0.200mm (7.87mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	(Mixed)				-	-
	1172 Total												

IMPEDANCE TABLE					
LAYER	TRACE mils	SPACING mils	IMPEDANCE (Single ended)	IMPEDANCE (Differentiel)	TOL.
TOP	27.55	9.84	50 ohm	NA	+/- 10%

PCB SPECIFICATIONS :

A. MATERIAL :

B. MATERIAL FAMILY :

C. SOLDERMASK COLOR :

D. SILKSCREEN COLOR :

E. SURFACE FINISH :

F. IMPEDANCE CONTROL :

G. THROUGH VIA :

H. STACK-UP :

FR-4

☒ TG-170

☐ TG-150

☐ TG-140

N/A

☒ GREEN

☐ BLUE

☐ RED

☐ BLACK

☒ WHITE

☐ YELLOW

☐ BLACK

☒ ENIG

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ HASL

☐ HASL (PB-FREE)

☐ GOLDEN FINGER

☐ NO

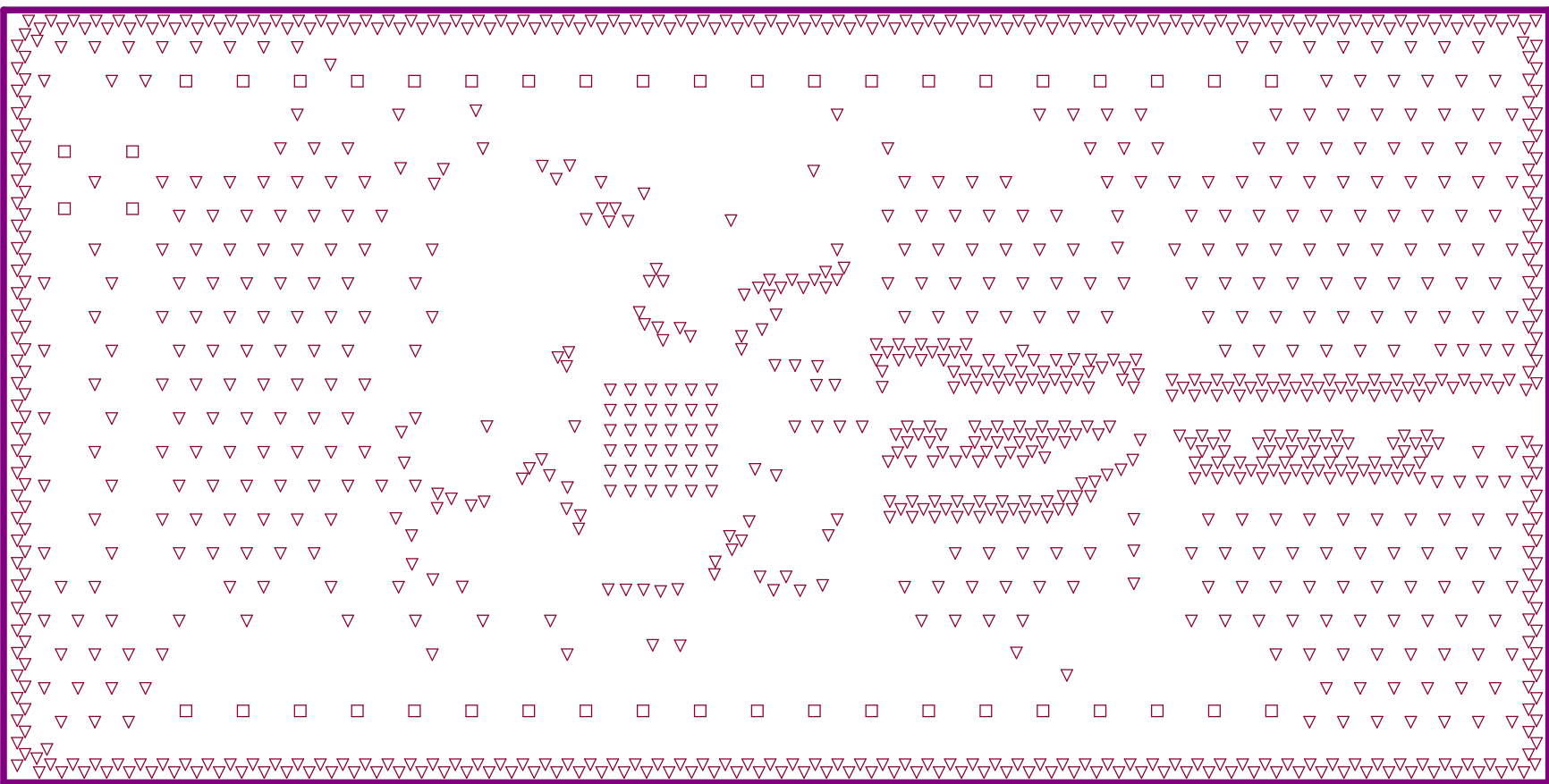
☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)


PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.

PLUG MATERIAL : ☒ SOLDERMASK

☐ NON-CONDUCTIVE EPOXY.

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.



Project: STM32WL-QFN48-2Layers_Reference_Board		
Layer: Drill Drawing	Gerber: .DRL	
Variant: [No Variations]	Ref: MB1791	
Date: 4-4-2022	Rev: A	